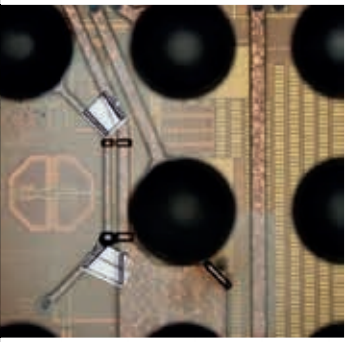
MASER
ENGINEERING

FIB CIRCUIT EDIT SERVICES

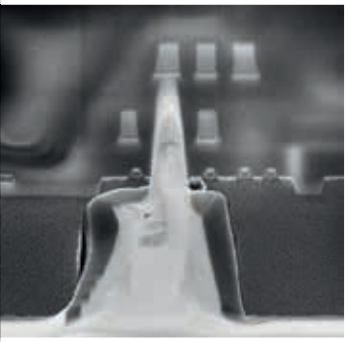
- DEDICATED FIB CIRCUIT EDIT SYSTEM
- UP TO 16 NM PROCESS NODES
- CAD NAVIGATION USING GDS-II FILES
- CAPABLE OF PERFORMING BACK-SIDE FIB CIRCUIT EDIT
- NIR MICROSCOPE FOR EASY NAVIGATION

FIB CIRCUIT EDIT SERVICES



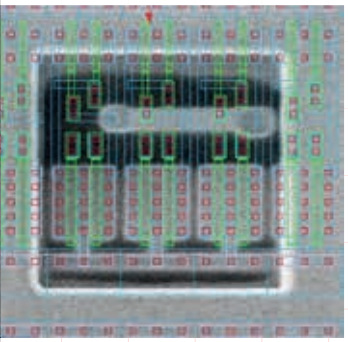
COPPER METAL SILICON EDIT

- Dedicated FIB Circuit Edit system: DCG systems OptiFIB IV
- Platinum and Molybdenum gas for conductive deposition
- Dual nozzle gas injection for uniform deposition/etching
- Up to 16 nm low-K process nodes
- CAD navigation using GDS-II files



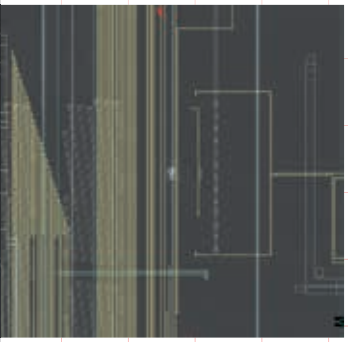
BACK-SIDE CIRCUIT EDIT

- Coaxial NIR microscope for localization
- Easy navigation using GDS-II overlay
- FIB Assisted end point detected
- Circuit edit on lower metal layers
- Mechanical silicon thinning before back-side FIB circuit edit



CAD NAVIGATION

- NIR microscope for alignment
- CAD navigation using GDS-II files
- Secure FTP server for GDS-II upload
- Fast and easy navigation
- Link FIB image to GDS file



DIFFERENT GASSES

- XeF2 for fast trenching/etching
- SiO2 dielectric deposition
- Platinum deposition
- Molybdenum deposition
- Copper etch gas
- Metal etch gas

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